

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	221	(semiconductor or electronic or circuit) same2 (solder\$3) same (wet\$4) with align\$5	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 16:18
L2	27	(semiconductor or electronic or circuit) same2 (solder\$3) same (wet\$4) with align\$5 same tension	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 16:38
L3	1	("2004/0089880").URPN.	USPAT	ADJ	ON	2008/11/26 16:40
S1	2	"20080011814"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 08:53
S2	1405	((circuit or electronic) near (device or component or board)) same (rectangular or rectangle or square) with (pad)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 08:58
S3	855	S2 and solder\$3	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 08:58
S4	90	"4404059"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 09:33
S5	89	"3801388"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 09:34

S6	53	"5738797"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 09:34
S7	11	("3801388"   "4404059"   "4561173"   "5738797"). PN. OR ("6111204"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/07/24 09:35
S8	64	("3292240"   "3303393"   "3320658"   "3339704"   "3367476"   "3373481"   "3387365"   "3392256"   "3392442"   "3461357"   "3591839"   "3646670"   "3780352"   "3795047"   "3871015"   "3975216"   "4231154"   "4251852"   "4329779"   "4377316"   "4480288"   "4512509"   "4517051"   "4545610"   "4549200"   "4628408"   "4642889"   "4646435"   "4681654"   "4692843"   "4857671").PN. OR ("5170931").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/07/24 13:27
S9	14	("20010029095"   "20020034872"   "20040087130"   "20040175917"   "20040209452"   "6297142"   "6413850"   "6564986"   "6656826"   "6846735"   "6884707"   "6897141"   "7078330"). PN. OR ("7217645"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/07/24 13:39
S10	1405	((circuit or electronic) near (device or component or board)) same (rectangular or rectangle or square) with (pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 13:58
S11	855	S10 and solder\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 13:58

S12	78	S11 and (orthogonal)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 13:58
S13	2	"20080011814"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 14:32
S14	1	S13 and h	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 14:32
S15	1	(US-5170931-\$).did.	USPAT	ADJ	ON	2008/07/24 14:33
S16	1	S15 and h	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 14:33
S17	965	(solder\$3 or bond\$3) near1 pad same (different or multi or multiple) with size	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 14:38
S18	474	(solder\$3 or bond\$3) near1 pad same (different or multi or multiple) near1 size	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 14:38
S19	2	"20010020747"	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 14:52
S20	1	S15 and square	USPAT	ADJ	ON	2008/07/24 15:00
S21	51	S12 and force	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 15:02

S22	50	(( "20030095755" ) or ("20040070400" ) or ("20040114259" ) or ("20050279170" ) or ("20060228066" ) or ("20060246630" ) or ("4274824" ) or ("4283278" ) or ("4317699" ) or ("4323979" ) or ("4330911" ) or ("4336470" ) or ("4339290" ) or ("4350276" ) or ("4364160" ) or ("4382749" ) or ("4384236" ) or ("4408092" ) or ("4416562" ) or ("4419816" ) or ("4430793" ) or ("4431267" ) or ("4432038" ) or ("4432587" ) or ("4440462" ) or ("4443168" ) or ("4453838" ) or ("4458958" ) or ("4472668" ) or ("4491078" ) or ("4498731" ) or ("4500274" ) or ("4512674" ) or ("4545110" ) or ("4545569" ) or ("4558620" ) or ("4581956" ) or ("4594792" ) or ("4602435" ) or ("4602456" ) or ("4610608" ) or ("4959005" ) or ("5905007" ) or ("6019212" ) or ("6084782" ) or ("6169827" ) or ("6287765" ) or ("6860648" ) or ("6998851" ) or ("7002730" )).PN.	US-PGPUB; USPAT; USOCR	:OR	:OFF	2008/07/24 15:16
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S23	2	(electronic or circuit) near1 (chip or component or board) same ((solder or bond\$3) near1 pad) with (different or multiple or multi) near1 (size) and force	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 15:18
S24	15	(electronic or circuit) near1 (chip or component or board) same ((solder or bond\$3) near1 pad) same (different or multiple or multi) near1 (size) and force	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 15:19
S25	54	(electronic or circuit) near1 (chip or component or board) same ((solder or bond\$3) near1 pad) same (different or multiple or multi) near1 (size)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 15:21
S26	97	(oggioni or albrecht or despont or lantz or castriotta).inv. and ((pad) and (component or chip) and solder)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 16:02
S27	379	S11 and (force or press)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 16:16
S28	85	S11 and (spacer)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 16:24
S29	15	S11 and (stopper)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 16:30
S30	3	("2002119597") or ("6125043") or ("2001033718") or ("4600970") or ("6239385").PN.	US_PGPUB; USPAT; USOCR	OR	OFF	2008/07/24 16:39

S31	5380	(MEMS or electronic component or electronic chip or semiconductor) and solder and (press or force) and (stopper or spacer)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 17:47
S32	1481	(MEMS or electronic component or electronic chip or semiconductor) and solder and (press or force) same (stopper or spacer)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 17:47
S33	624	(MEMS or electronic component or electronic chip or semiconductor) same solder and (press or force) same (stopper or spacer)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/24 17:48
S34	0	("2004/0251540").URPN.	USPAT	ADJ	ON	2008/07/24 17:59
S35	4	("6125043") or ("6239385") or ("20020119597") or ("20010033718")).PN.	US_PGPUB; USPAT; USOCR	OR	OFF	2008/07/24 18:02
S36	26	("3436615"   "3811186"   "4184043"   "5011066"   "5220200"   "5311399"   "5519580"   "5889326"   "5929521"   "5968670"). PN. OR ("6125043"). URPN.	US_PGPUB; USPAT; USOCR	ADJ	ON	2008/07/24 18:03
S37	1	("6125043").PN.	US_PGPUB; USPAT; USOCR	OR	OFF	2008/07/25 10:47
S38	389	(electronic component and solder pad and solder and press)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/25 10:48
S39	890	thermo\$1compression near (bond\$3) same (electronic)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/07/25 11:00

11/26/2008 4:50:30 PM

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